the pre-alignment station 39, after the wafer 4 is held with a chuck 8, an alignment optical system 9 - 11 detects a wafer edge position while the wafer 4 is rotated by a θ-stage 7. Detection signals are produced and processed to calculate an orientation flat 4a direction and an off-center deviation of the wafer 4 held by the chuck 8, in order to align the wafer 4 using an X-stage 5, a Y-stage 6 and the θ-stage 7. The above-mentioned operation is a so-called "orientation flat detection" operation. After the pre-alignment, the wafer 4 is transferred to a wafer chuck 12 of an exposure station 13 and an exposure operation is performed in a step-and-repeat manner using an XY-stage 14. Thereafter, the handling robot 1 withdraws the exposed wafer to return it to another cassette 3. The foregoing elements are housed in a clean room environment 100. --

G1

Please replace the paragraph starting at page 6, line 26, and ending on page 7, line 3, with the following paragraph. A marked-up copy of the paragraph showing the changes made thereto is attached in Appendix A.

-- FIG. 1 illustrates a structure of an exposure apparatus 110 for manufacturing micro-devices using a front open type pod (FOUP) as a mini-environment pod 20, according to an embodiment of the present invention. While the exposure apparatus 110 is one example of a micro-device manufacturing apparatus that is suitably usable, the present invention is applicable to any type of micro-device manufacturing apparatus using mini-environment pods, e.g., a resist coating apparatus, a developing apparatus, a heating apparatus, an inspection apparatus, etc. --

G2